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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	42
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1114fbd48-302-1

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

32-bit ARM Cortex-M0 microcontroller

Type number	Package							
	Name	Description	Version					
LPC1115JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 \times 7 \times 1.4 mm	SOT313-2					
LPC1115FET48/303	TFBGA48	plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 \times 4.5 \times 0.7 mm	SOT1155-2					
LPC1115JET48/303	TFBGA48	plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 \times 4.5 \times 0.7 mm	SOT1155-2					

Table 1. Ordering information ... continued

4.1 Ordering options

Table 2. Ordering options

Type number	Series	Flash	Total SRAM	Power profiles	UART	l ² C/ Fast+	SPI	ADC channel	GPIO	Package	Temp <u>^[1]</u>
LPC1110											
LPC1110FD20	LPC1100L	4 kB	1 kB	100	1	1	1	5	16	SO20	F
LPC1111	LFCIIUUL	4 KD	IKD	yes	I	I	I	5	10	3020	Г
	LPC1100L	0.1-D			4	4	4	5	40	TSSOP20	F
LPC1111FDH20/002		8 kB	2 kB	yes	1	1	1		16		
LPC1111FHN33/101	LPC1100	8 kB	2 kB	no	1	1	1	8	28		F
LPC1111FHN33/102	LPC1100L	8 kB	2 kB	yes	1	1	1	8	28	HVQFN33	
LPC1111FHN33/103	LPC1100XL	8 kB	2 kB	yes	1	1	2	8	28	HVQFN33	
LPC1111JHN33/103	LPC1100XL	8 kB	2 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1111FHN33/201	LPC1100	8 kB	4 kB	no	1	1	1	8	28	HVQFN33	
LPC1111FHN33/202	LPC1100L	8 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1111FHN33/203	LPC1100XL	8 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1111JHN33/203	LPC1100XL	8 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112											
LPC1112FD20/102	LPC1100L	16 kB	4 kB	yes	1	1	1	5	16	SO20	F
LPC1112FDH20/102	LPC1100L	16 kB	4 kB	yes	1	-	1	5	14	TSSOP20	F
LPC1112FDH28/102	LPC1100L	16 kB	4 kB	yes	1	1	1	6	22	TSSOP28	F
LPC1112FHN24/202	LPC1100L	16 kB	4 kB	yes	1	1	1	6	19	HVQFN24	F
LPC1112FHN33/101	LPC1100	16 kB	2 kB	no	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/102	LPC1100L	16 kB	2 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/103	LPC1100XL	16 kB	2 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHN33/103	LPC1100XL	16 kB	2 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112FHN33/201	LPC1100	16 kB	4 kB	no	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/202	LPC1100L	16 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHN33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHN33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J
LPC1112FHI33/102	LPC1100L	16 kB	2 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHI33/202	LPC1100L	16 kB	4 kB	yes	1	1	1	8	28	HVQFN33	F
LPC1112FHI33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	F
LPC1112JHI33/203	LPC1100XL	16 kB	4 kB	yes	1	1	2	8	28	HVQFN33	J

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LPC1100L series: LPC1110/11/12 pin description table (SO20 and TSSOP20 package with Table 4. I²C-bus pins) ... continued

I ² C-bus pins)continued						
Symbol	Pin SO20/ TSSOP20		Start logic input	Туре	Reset state [1]	Description
R/PIO0_11/ AD0/CT32B0_MAT3	4	<u>[5]</u>	yes	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	PIO0_11 — General purpose digital input/output pin.
				I	-	AD0 — A/D converter, input 0.
				0	-	CT32B0_MAT3 — Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_7				I/O		Port 1 — Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/ AD1/CT32B1_CAP0	7	<u>[5]</u>	yes	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	PIO1_0 — General purpose digital input/output pin.
				I	-	AD1 — A/D converter, input 1.
				I	-	CT32B1_CAP0 — Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	8	[5]	no	0	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	PIO1_1 — General purpose digital input/output pin.
				I	-	AD2 — A/D converter, input 2.
				0	-	CT32B1_MAT0 — Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	9	[5]	no	I	I; PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.
				I/O	-	PIO1_2 — General purpose digital input/output pin.
				I	-	AD3 — A/D converter, input 3.
				0	-	CT32B1_MAT1 — Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/	10	[5]	no	I/O	I; PU	SWDIO — Serial wire debug input/output.
AD4/CT32B1_MAT2				I/O	-	PIO1_3 — General purpose digital input/output pin.
				I	-	AD4 — A/D converter, input 4.
				0	-	CT32B1_MAT2 — Match output 2 for 32-bit timer 1.
PIO1_6/RXD/	11	[3]	no	I/O	I; PU	PIO1_6 — General purpose digital input/output pin.
CT32B0_MAT0				I	-	RXD — Receiver input for UART.
				0	-	CT32B0_MAT0 — Match output 0 for 32-bit timer 0.
PIO1_7/TXD/	12	[3]	no	I/O	I; PU	PIO1_7 — General purpose digital input/output pin.
CT32B0_MAT1				0	-	TXD — Transmitter output for UART.
				0	-	CT32B0_MAT1 — Match output 1 for 32-bit timer 0.
V _{DD}	15		-		-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	14	[6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	13	[6]	-	0	-	Output from the oscillator amplifier.
V _{SS}	16		-		-	Ground.

LPC111X Product data sheet

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Symbol	Pin	Start logic input	Туре	Reset state [1]	Description
PIO3_0 to PIO3_5			I/O		Port 3 — Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_6 to PIO3_11 are not available.
PIO3_0/DTR	36 <u>[3]</u>	no	I/O	I; PU	PIO3_0 — General purpose digital input/output pin.
			0	-	DTR — Data Terminal Ready output for UART.
PIO3_1/DSR	37 <u>[3]</u>	no	I/O	I; PU	PIO3_1 — General purpose digital input/output pin.
			I	-	DSR — Data Set Ready input for UART.
PIO3_2/DCD	43 <u>[3]</u>	no	I/O	I; PU	PIO3_2 — General purpose digital input/output pin.
			I	-	DCD — Data Carrier Detect input for UART.
PIO3_3/RI	48 <u>[3]</u>	no	I/O	I; PU	PIO3_3 — General purpose digital input/output pin.
			I	-	RI — Ring Indicator input for UART.
PIO3_4	18 <u>^[3]</u>	no	I/O	I; PU	PIO3_4 — General purpose digital input/output pin.
PIO3_5	21 <u>[3]</u>	no	I/O	I; PU	PIO3_5 — General purpose digital input/output pin.
V _{DD}	8; 44	-	I	-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	6 <u>[6]</u>	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	7 <u>[6]</u>	-	0	-	Output from the oscillator amplifier.
V _{SS}	5; 41	-	I	-	Ground.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package) ...continued

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to 2.6 V for LPC111x/101/201/301, pins pulled up to full V_{DD} level on LPC111x/002/102/202/302 (V_{DD} = 3.3 V)); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. RESET functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See <u>Figure 52</u> for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I²C-bus pads compliant with the I²C-bus specification for I²C standard mode and I²C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see <u>Figure 51</u>).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

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Symbol	Pin	Start logic input	Туре	Reset state [1]	Description	
PIO0_0 to PIO0_11					Port 0 — Port 0 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 0 pins depends on the function selected through the IOCONFIG register block.	
RESET/PIO0_0	2[2]	yes	1	I;PU	RESET — External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states and processor execution to begin at address 0.	
					In deep power-down mode, this pin must be pulled HIGH externally. The RESET pin can be left unconnected or be used as a GPIO pin if an external RESET function is not needed and Deep power-down mode is not used.	
			I/O	-	PIO0_0 — General purpose digital input/output pin with 10 ns glitch filter.	
PIO0_1/CLKOUT/ CT32B0_MAT2	3 <u>[3]</u>	yes	I/O	I;PU	PIO0_1 — General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.	
			0	-	CLKOUT — Clock out pin.	
			0	-	CT32B0_MAT2 — Match output 2 for 32-bit timer 0.	
PIO0_2/SSEL0/	8 <u>[3]</u>	yes	I/O	I;PU	PIO0_2 — General purpose digital input/output pin.	
CT16B0_CAP0			I/O	-	SSEL0 — Slave select for SPI0.	
			I	-	CT16B0_CAP0 — Capture input 0 for 16-bit timer 0.	
PIO0_3	9 <u>[3]</u>	yes	I/O	I;PU	PIO0_3 — General purpose digital input/output pin.	
PIO0_4/SCL	10 <u>[4]</u>	yes	I/O	I;IA	PIO0_4 — General purpose digital input/output pin (open-drain).	
			I/O	-	$\label{eq:scl} \begin{array}{l} \textbf{SCL} & = I^2 C \text{-bus, open-drain clock input/output. High-current sink only} \\ \text{if } I^2 C \text{ Fast-mode Plus is selected in the I/O configuration register.} \end{array}$	
PIO0_5/SDA	11 <u>^[4]</u>	yes	I/O	I;IA	PIO0_5 — General purpose digital input/output pin (open-drain).	
			I/O	-	SDA — I^2C -bus, open-drain data input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.	
PIO0_6/SCK0	15 <u>[3]</u>	yes	I/O	I;PU	PIO0_6 — General purpose digital input/output pin.	
			I/O	-	SCK0 — Serial clock for SPI0.	
PIO0_7/CTS	16 <u>[3]</u>	yes	I/O	I;PU	PIO0_7 — General purpose digital input/output pin (high-current output driver).	
			I	-	CTS — Clear To Send input for UART.	
PIO0_8/MISO0/	17 <u>[3]</u>	yes	I/O	I;PU	PIO0_8 — General purpose digital input/output pin.	
CT16B0_MAT0			I/O	-	MISO0 — Master In Slave Out for SPI0.	
			0	-	CT16B0_MAT0 — Match output 0 for 16-bit timer 0.	
PIO0_9/MOSI0/	18 <u>[3]</u>	yes	I/O	I;PU	PIO0_9 — General purpose digital input/output pin.	
CT16B0_MAT1			I/O	-	MOSI0 — Master Out Slave In for SPI0.	
			0	-	CT16B0_MAT1 — Match output 1 for 16-bit timer 0.	
SWCLK/PIO0_10/	19 <u>[3]</u>	yes	I	I;PU	SWCLK — Serial wire clock.	
SCK0/			I/O	-	PIO0_10 — General purpose digital input/output pin.	
CT16B0_MAT2			I/O	-	SCK0 — Serial clock for SPI0.	
			0	-	CT16B0_MAT2 — Match output 2 for 16-bit timer 0.	

Table 9. LPC1100 and LPC1100L series: LPC1111/12/13/14 pin description table (HVQFN33 package)

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Symbol	Pin	Start logic input	Туре	Reset state [1]	Description		
R/PIO0_11/AD0/ CT32B0_MAT3	21 <u>5</u>]	yes	-	I;PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.		
			I/O	-	PIO0_11 — General purpose digital input/output pin.		
			I	-	AD0 — A/D converter, input 0.		
			0	-	CT32B0_MAT3 — Match output 3 for 32-bit timer 0.		
PIO1_0 to PIO1_11					Port 1 — Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.		
R/PIO1_0/AD1/ CT32B1_CAP0	22 ^[5]	yes	-	I;PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.		
			I/O	-	PIO1_0 — General purpose digital input/output pin.		
			I	-	AD1 — A/D converter, input 1.		
			I	-	CT32B1_CAP0 — Capture input 0 for 32-bit timer 1.		
R/PIO1_1/AD2/ CT32B1_MAT0	23 <u>[5]</u>	no	-	I;PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.		
			I/O	-	PIO1_1 — General purpose digital input/output pin.		
			I	-	AD2 — A/D converter, input 2.		
			0	-	CT32B1_MAT0 — Match output 0 for 32-bit timer 1.		
R/PIO1_2/AD3/ CT32B1_MAT1	24 <u>^[5]</u>	no	-	I;PU	R — Reserved. Configure for an alternate function in the IOCONFIG block.		
			I/O	-	PIO1_2 — General purpose digital input/output pin.		
			I	-	AD3 — A/D converter, input 3.		
			0	-	CT32B1_MAT1 — Match output 1 for 32-bit timer 1.		
SWDIO/PIO1_3/	25 <u>[5]</u>	no	I/O	I;PU	SWDIO — Serial wire debug input/output.		
AD4/CT32B1_MAT2			I/O	-	PIO1_3 — General purpose digital input/output pin.		
			I	-	AD4 — A/D converter, input 4.		
			0	-	CT32B1_MAT2 — Match output 2 for 32-bit timer 1.		
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	26 ^[5]	no	I/O	I;PU	PIO1_4 — General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.		
			I	-	AD5 — A/D converter, input 5.		
			0	-	CT32B1_MAT3 — Match output 3 for 32-bit timer 1.		
PIO1_5/RTS/	30 <u>[3]</u>	no	I/O	I;PU	PIO1_5 — General purpose digital input/output pin.		
CT32B0_CAP0			0	-	RTS — Request To Send output for UART.		
			I	-	CT32B0_CAP0 — Capture input 0 for 32-bit timer 0.		
PIO1_6/RXD/	31 <u>[3]</u>	no	I/O	I;PU	PIO1_6 — General purpose digital input/output pin.		
CT32B0_MAT0			I	-	RXD — Receiver input for UART.		
			0	-	CT32B0_MAT0 — Match output 0 for 32-bit timer 0.		

Table 11. LPC1100XL series: LPC1111/12/13/14 pin description table (HVQFN33 package) ...continued

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7. Functional description

7.1 ARM Cortex-M0 processor

The ARM Cortex-M0 is a general purpose, 32-bit microprocessor, which offers high performance and very low power consumption.

7.2 On-chip flash program memory

The LPC1110/11/12/13/14/15 contain 64 kB (LPC1115), 56 kB (LPC1114/333), 48 kB (LPC1114/323), 32 kB (LPC1114), 24 kB (LPC1113), 16 kB (LPC1112), 8 kB (LPC1111) or 4 kB (LPC1110) of on-chip flash memory.

7.3 On-chip SRAM

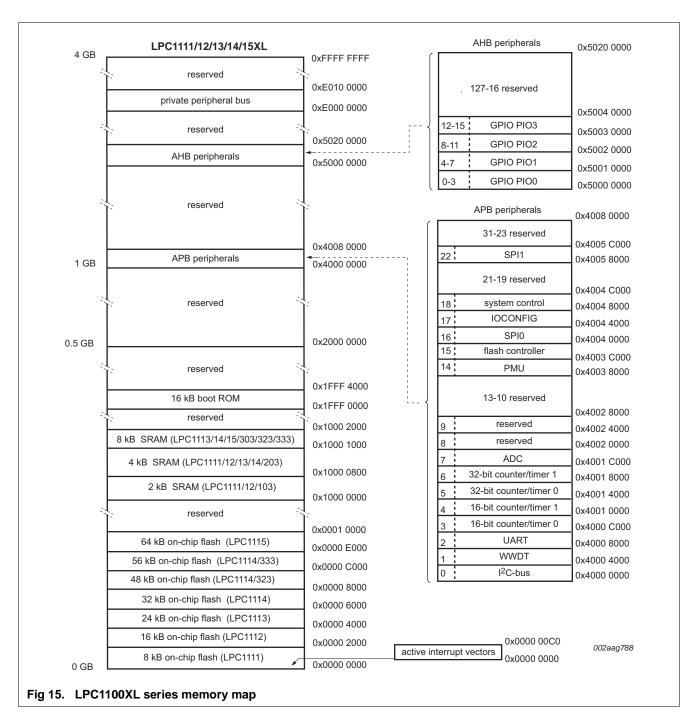
The LPC1110/11/12/13/14/15 contain a total of 8 kB, 4 kB, 2 kB, or 1 kB on-chip static RAM memory.

7.4 Memory map

The LPC1110/11/12/13/14/15 incorporate several distinct memory regions, shown in the following figures. Figure 14 shows the overall map of the entire address space from the user program viewpoint following reset. The interrupt vector area supports address remapping.

The AHB peripheral area is 2 MB in size, and is divided to allow for up to 128 peripherals. The APB peripheral area is 512 kB in size and is divided to allow for up to 32 peripherals. Each peripheral of either type is allocated 16 kB of space. This allows simplifying the address decoding for each peripheral.

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7.5 Nested Vectored Interrupt Controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is an integral part of the Cortex-M0. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

7.5.1 Features

• Controls system exceptions and peripheral interrupts.

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- In the LPC1110/11/12/13/14/15, the NVIC supports 32 vectored interrupts including up to 13 inputs to the start logic from individual GPIO pins.
- Four programmable interrupt priority levels with hardware priority level masking.
- Software interrupt generation.

7.5.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

Any GPIO pin (total of up to 42 pins) regardless of the selected function, can be programmed to generate an interrupt on a level, or rising edge or falling edge, or both.

7.6 IOCONFIG block

The IOCONFIG block allows selected pins of the microcontroller to have more than one function. Configuration registers control the multiplexers to allow connection between the pin and the on-chip peripherals.

Peripherals should be connected to the appropriate pins prior to being activated and prior to any related interrupt(s) being enabled. Activity of any enabled peripheral function that is not mapped to a related pin should be considered undefined.

7.7 Fast general purpose parallel I/O

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Multiple outputs can be set or cleared in one write operation.

LPC1110/11/12/13/14/15 use accelerated GPIO functions:

- GPIO registers are a dedicated AHB peripheral so that the fastest possible I/O timing can be achieved.
- Entire port value can be written in one instruction.

Additionally, any GPIO pin (total of up to 42 pins) providing a digital function can be programmed to generate an interrupt on a level, a rising or falling edge, or both.

7.7.1 Features

- Bit level port registers allow a single instruction to set or clear any number of bits in one write operation.
- Direction control of individual bits.
- All I/O default to inputs with pull-ups enabled after reset with the exception of the I²C-bus pins PIO0_4 and PIO0_5.
- Pull-up/pull-down resistor configuration can be programmed through the IOCONFIG block for each GPIO pin (except for pins PIO0_4 and PIO0_5).
- On the LPC1100, all GPIO pins (except PIO0_4 and PIO0_5) are pulled up to 2.6 V (V_{DD} = 3.3 V) if their pull-up resistor is enabled in the IOCONFIG block.

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- Optional conversion on transition of input pin or timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.12 General purpose external event counter/timers

The LPC1110/11/12/13/14/15 include two 32-bit counter/timers and two 16-bit counter/timers. The counter/timer is designed to count cycles of the system derived clock. It can optionally generate interrupts or perform other actions at specified timer values, based on four match registers. Each counter/timer also includes up to two capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt.

7.12.1 Features

- A 32-bit/16-bit timer/counter with a programmable 32-bit/16-bit prescaler.
- Counter or timer operation.
- Up to two capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event may also generate an interrupt.
- The timer and prescaler may be configured to be cleared on a designated capture event. This feature permits easy pulse width measurement by clearing the timer on the leading edge of an input pulse and capturing the timer value on the trailing edge.
- Four match registers per timer that allow:
 - Continuous operation with optional interrupt generation on match.
 - Stop timer on match with optional interrupt generation.
 - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
 - Set LOW on match.
 - Set HIGH on match.
 - Toggle on match.
 - Do nothing on match.

7.13 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

7.14 Watchdog timer (LPC1100 series, LPC111x/101/201/301)

Remark: The watchdog timer without windowed features is available on parts LPC111x/101/201/301.

The purpose of the watchdog is to reset the microcontroller within a selectable time period.

7.14.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.

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The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL.

7.16.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 9.4 kHz and 2.3 MHz. The frequency spread over processing and temperature is \pm 40 %.

7.16.2 System PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The PLL output frequency must be lower than 100 MHz. The output divider may be set to divide by 2, 4, 8, or 16 to produce the output clock. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μ s.

7.16.3 Clock output

The LPC1110/11/12/13/14/15 features a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

7.16.4 Wake-up process

The LPC1110/11/12/13/14/15 begin operation at power-up and when awakened from Deep power-down mode by using the 12 MHz IRC oscillator as the clock source. This allows chip operation to resume quickly. If the system oscillator or the PLL is needed by the application, software will need to enable these features and wait for them to stabilize before they are used as a clock source.

7.16.5 Power control

The LPC1110/11/12/13/14/15 support a variety of power control features. There are three special modes of processor power reduction: Sleep mode, Deep-sleep mode, and Deep power-down mode. The CPU clock rate may also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals, allowing fine tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Selected peripherals have their own clock divider which provides even better power control.

7.16.5.1 Power profiles (LPC1100L and LPC1100XL series only)

The power consumption in Active and Sleep modes can be optimized for the application through simple calls to the power profile. The power configuration routine configures the LPC1110/11/12/13/14/15 for one of the following power modes:

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9. Thermal characteristics

The average chip junction temperature, $T_{j}\,(^{\circ}C),$ can be calculated using the following equation:

$$T_j = T_{amb} + (P_D \times R_{th(j-a)}) \tag{1}$$

- T_{amb} = ambient temperature (°C),
- R_{th(j-a)} = the package junction-to-ambient thermal resistance (°C/W)
- P_D = sum of internal and I/O power dissipation

The internal power dissipation is the product of I_{DD} and V_{DD} . The I/O power dissipation of the I/O pins is often small and many times can be negligible. However it can be significant in some applications.

Table 13. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T _{j(max)}	maximum junction		-	-	125	°C
	temperature					

Table 14. LPC111x/x01 Thermal resistance value (°C/W): ±15 %

HVQFN33		LQFP48	LQFP48			
θја	θja					
JEDEC (4.5 in × 4 in)		JEDEC (4.5 in × 4 in)				
0 m/s	40.4	0 m/s	82.1			
1 m/s	32.7	1 m/s	73.7			
2.5 m/s	28.3	2.5 m/s	68.2			
Single-layer (4.5 in \times 3 in)	8-layer (4.5 in × 3 in)				
0 m/s	84.8	0 m/s	115.2			
1 m/s	61.6	1 m/s	94.7			
2.5 m/s	53.1	2.5 m/s	86.3			
өјс	20.3	өјс	29.6			
θjb	1.1	θjb	34.2			

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Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V _{IL}	LOW-level input voltage		-	-	0.3V _{DD}	V
V _{hys}	hysteresis voltage		-	0.4	-	V
V _{OH}	HIGH-level output voltage	$\begin{array}{l} 2.5 \ V \leq V_{DD} \leq 3.6 \ V; \\ I_{OH} = -4 \ mA \end{array} \label{eq:VDD}$	$V_{DD}-0.4$	-	-	V
		$\begin{array}{l} 1.8 \ \text{V} \leq \text{V}_{\text{DD}} < 2.5 \ \text{V}; \\ \text{I}_{\text{OH}} = -3 \ \text{mA} \end{array}$	$V_{DD}-0.4$	-	-	V
V _{OL}	LOW-level output voltage	$\begin{array}{l} 2.5 \ V \leq V_{DD} \leq 3.6 \ V; \\ I_{OL} = 4 \ mA \end{array} \label{eq:VDD}$	-	-	0.4	V
		$1.8 \text{ V} \leq \text{V}_{\text{DD}} < 2.5 \text{ V}; \\ \text{I}_{\text{OL}} = 3 \text{ mA}$	-	-	0.4	V
I _{OH}	HIGH-level output current	$V_{OH} = V_{DD} - 0.4 V;$ 2.5 V $\leq V_{DD} \leq 3.6 V$	-4	-	-	mA
		$1.8 \text{ V} \le \text{V}_{\text{DD}}$ < 2.5 V	-3	-	-	mA
I _{OL}	LOW-level output current	$V_{OL} = 0.4 V$ 2.5 V $\leq V_{DD} \leq 3.6 V$	4	-	-	mA
		$1.8 \text{ V} \le \text{V}_{\text{DD}} < 2.5 \text{ V}$	3	-	-	mA
I _{OHS}	HIGH-level short-circuit output current	V _{OH} = 0 V [16]	-	-	-45	mA
I _{OLS}	LOW-level short-circuit output current	$V_{OL} = V_{DD} $ [16]	-	-	50	mA
I _{pd}	pull-down current	V ₁ = 5 V	10	50	150	μA
I _{pu}	pull-up current	$V_{I} = 0 V;$	-15	-50	-85	μA
		$2.0~V \leq V_{DD} \leq 3.6~V$				
		$1.8~\text{V} \leq \text{V}_{\text{DD}} < 2.0~\text{V}$	-10	-50	-85	μA
		$V_{DD} < V_{I} < 5 V$	0	0	0	μA
High-drive o	output pin (PIO0_7)					
I _{IL}	LOW-level input current	V _I = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I _{IH}	HIGH-level input current	V _I = V _{DD} ; on-chip pull-down resistor disabled	-	0.5	10	nA
I _{OZ}	OFF-state output current	$V_O = 0 V$; $V_O = V_{DD}$; on-chip pull-up/down resistors disabled	-	0.5	10	nA
VI	input voltage	pin configured to provide [13][14] a digital function [15]	-	-	5.0	V
Vo	output voltage	output active	0	-	V _{DD}	V
V _{IH}	HIGH-level input voltage		0.7V _{DD}	-	-	V
V _{IL}	LOW-level input voltage		-	-	0.3V _{DD}	V
V _{hys}	hysteresis voltage		0.4	-	-	V

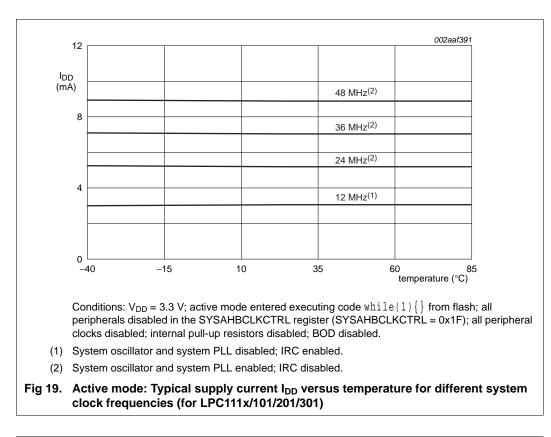
Table 17. Static characteristics (LPC1100XL series) ... continued $T_{amb} = -40 \ ^{\circ}C$ to +105 $^{\circ}C$. unless otherwise specified.

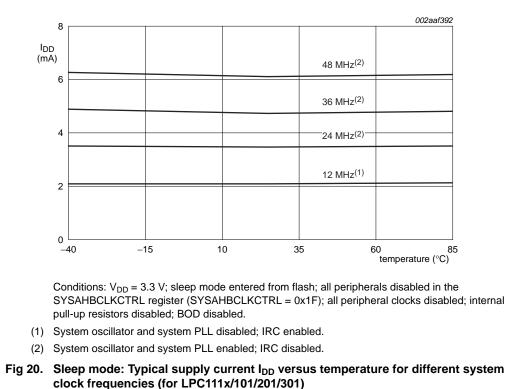
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Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V _{OH}	HIGH-level output voltage	$\begin{array}{l} 2.5 \ V \leq V_{DD} \leq 3.6 \ V; \\ I_{OH} = -20 \ mA \end{array} \label{eq:VDD}$	$V_{DD} - 0.4$	-	-	V
		$\begin{array}{l} 1.8 \ \text{V} \leq \text{V}_{\text{DD}} < 2.5 \ \text{V}; \\ \text{I}_{\text{OH}} = -12 \ \text{mA} \end{array}$	$V_{DD}-0.4$	-	-	V
V _{OL}	LOW-level output voltage	$\begin{array}{l} 2.5 \ V \leq V_{DD} \leq 3.6 \ V; \\ I_{OL} = 4 \ mA \end{array} \label{eq:VDD}$	-	-	0.4	V
		$\begin{array}{l} 1.8 \ \text{V} \leq \text{V}_{\text{DD}} < 2.5 \ \text{V}; \\ \text{I}_{\text{OL}} = 3 \ \text{mA} \end{array}$	-	-	0.4	V
I _{OH}	HIGH-level output current		20	-	-	mA
		$1.8 \text{ V} \leq \text{V}_{\text{DD}} < 2.5 \text{ V}$	12	-	-	mA
I _{OL}	LOW-level output current	$V_{OL} = 0.4 \text{ V}$ 2.5 V $\leq V_{DD} \leq 3.6 \text{ V}$	4	-	-	mA
		$1.8 \text{ V} \leq \text{V}_{\text{DD}}$ < 2.5 V	3	-	-	mA
I _{OLS}	LOW-level short-circuit output current	$V_{OL} = V_{DD} $ ^[16]	-	-	50	mA
I _{pd}	pull-down current	V ₁ = 5 V	10	50	150	μA
I _{pu}	pull-up current	$V_{I} = 0 V$ $2.0 V \leq V_{DD} \leq 3.6 V$	-15	-50	-85	μA
		$1.8 \text{ V} \le \text{V}_{\text{DD}}$ < 2.0 V	-10	-50	-85	μA
		$V_{DD} < V_I < 5 V$	0	0	0	μA
I ² C-bus pin	ns (PIO0_4 and PIO0_5)	l	1	1		
V _{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
V _{IL}	LOW-level input voltage		-	-	0.3V _{DD}	V
V _{hys}	hysteresis voltage		-	$0.05V_{DD}$	-	V
I _{OL}	LOW-level output current	$V_{OL} = 0.4$ V; l ² C-bus pins configured as standard mode pins	3.5	-	-	mA
		$2.5 V \le V_{DD} \le 3.6 V$ 1.8 V \le V_{DD} < 2.5 V	3			
I _{OL}	LOW-level output	V _{OL} = 0.4 V; I ² C-bus pins	20	-	-	mA
	current	configured as Fast-mode Plus pins				
		$2.5~V \leq V_{DD} \leq 3.6~V$				
		$1.8 \text{ V} \leq \text{V}_{\text{DD}} < 2.5 \text{ V}$	16	-	-	
ILI	input leakage current	$V_{I} = V_{DD} $ [17]	-	2	4	μA
		$V_{I} = 5 V$	-	10	22	μA

Table 17. Static characteristics (LPC1100XL series) ... continued $r_{\rm mb} = -40 \ ^{\circ}{\rm C}$ to +105 $^{\circ}{\rm C}$, unless otherwise specified. Τ

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10.7 Power consumption LPC1100XL series (LPC111x/103/203/303/323/333)

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Table 20.	Power consumption at ver	y low frequencies	using the watchdog oscillator

Symbol	Parameter	Conditions ^[1]	Min	Typ[2]	Max	Unit
I _{DD}	supply current	Active mode; code				
		while(1){}				
		executed from flash				
		system clock = 8.8 kHz	-	275	-	μA
		system clock = 257 kHz	-	305	-	μA
		system clock = 515 kHz	-	335	-	μA
		system clock = 784 kHz	-	368	-	μA
		system clock = 1028 kHz	-	396	-	μA
		system clock = 2230 kHz	-	538	-	μA
		Sleep mode;				
		system clock = 8.8 kHz	-	274	-	μA
		system clock = 257 kHz	-	285	-	μA
		system clock = 515 kHz	-	295	-	μA
		system clock = 784 kHz	-	309	-	μA
		system clock = 1028 kHz	-	317	-	μA
		system clock = 2230 kHz	-	368	-	μA

[1] WDT OSC enabled, V_{DD} = 3.3 V, Temp = 25 $^\circ\text{C}.$

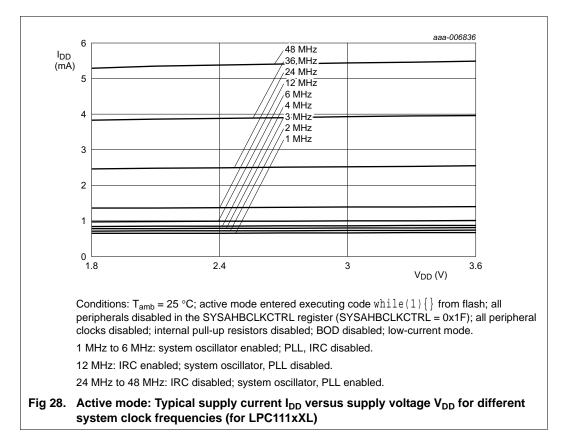
Low-current mode PWR_LOW_CURRENT selected when running the set_power routine in the power profiles. I_{DD} measurements were performed with all pins configured as GPIO outputs driven LOW and pull-up resistors disabled, IRC disabled, System Oscillator disabled, System PLL disabled, BOD disabled. All peripherals disabled in the SYSAHBCLKCTRL register. Peripheral clocks to UART and SPI0/1 disabled in system configuration block.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

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Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC111x user manual*):

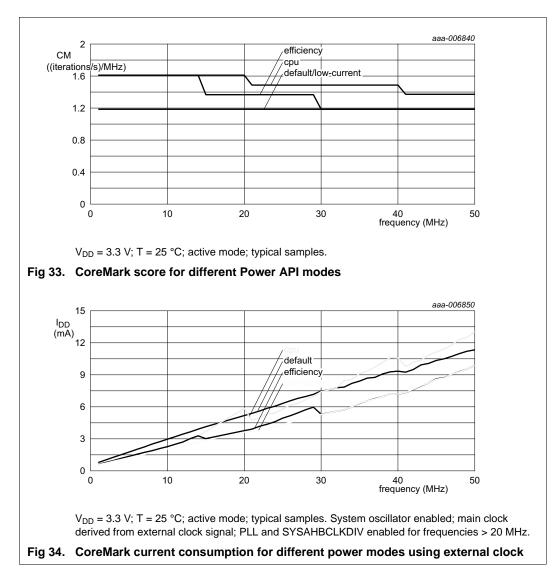
- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIOnDIR registers.
- Write 0 to all GPIOnDATA registers to drive the outputs LOW.



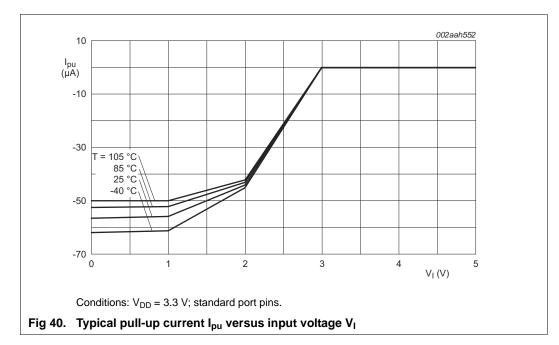
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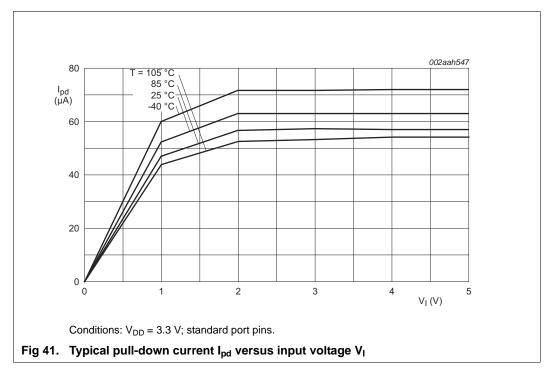
10.8 CoreMark data

Remark: All CoreMark data were taken with the Keil uVision v. 4.6 tool.



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Product data sheet

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11. Dynamic characteristics

11.1 Power-up ramp conditions

Table 22. Power-up characteristics^[1]

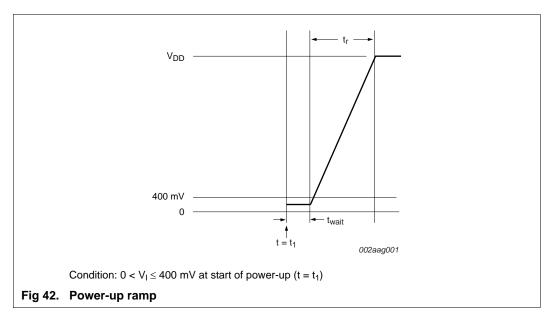
 $T_{amb} = -40 \ ^{\circ}C \ to +85 \ ^{\circ}C.$

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
t _r	rise time	at t = t_1 : 0 < V _I \le 400 mV	[2]	0	-	500	ms
t _{wait}	wait time		[2][3]	12	-	-	μS
VI	input voltage	at t = t_1 on pin V_{DD}		0	-	400	mV

[1] Does not apply to the LPC1100XL series (LPC111x/103/203/303/323/333).

[2] See <u>Figure 42</u>.

[3] The wait time specifies the time the power supply must be at levels below 400 mV before ramping up.



11.2 Flash memory

Table 23. Flash characteristics

 $T_{amb} = -40 \text{ }^{\circ}\text{C}$ to +105 $\text{ }^{\circ}\text{C}$, unless otherwise specified. $T_{amb} = 85 \text{ }^{\circ}\text{C}$ for flash programming.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
N _{endu}	endurance		[1]	10000	100000	-	cycles
t _{ret}	retention time	powered		10	-	-	years
		unpowered		20	-	-	years
t _{er}	erase time	sector or multiple consecutive sectors		95	100	105	ms
t _{prog}	programming time		[2]	0.95	1	1.05	ms

[1] Number of program/erase cycles.

[2] Programming times are given for writing 256 bytes from RAM to the flash. Data must be written to the flash in blocks of 256 bytes. Flash programming operation temperature must not exceed $T_{amb} = 85$ °C.

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13. Package outline

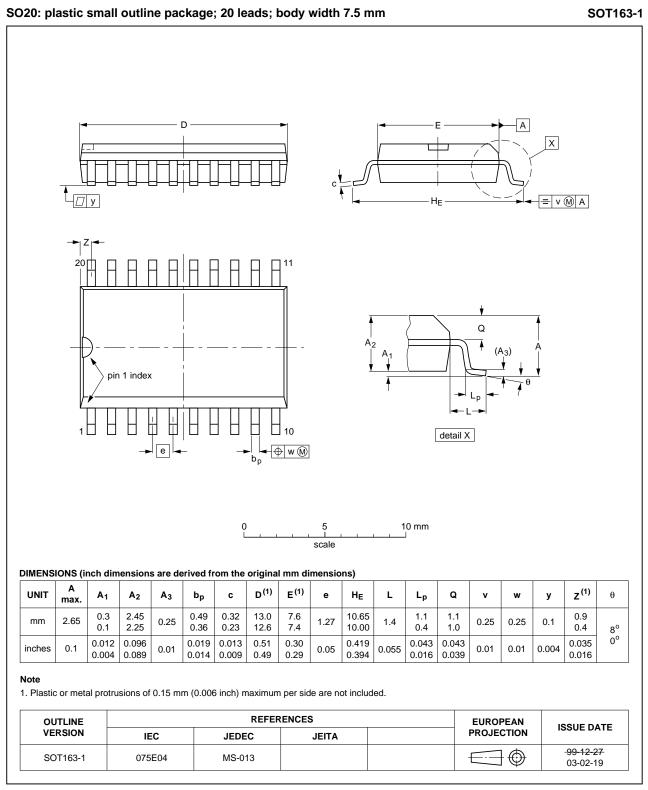


Fig 54. Package outline SOT163-1 (SO20)

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